### **EMI Common Mode Choke**



#### **BWCU Series**



#### Overview

An EMI common mode choke (CMC) for power lines is a passive component specifically designed to suppress electromagnetic interference (EMI) in power supply circuits

A full series of common mode choke is designed for excellent noise attenuation with compact sizing for use in wide range of applications. Both standard series and custom designs are available.

#### **Benefits**

- 1. EMI/RFI Suppression
- 2. Improved Signal Integrity
- 3. Effectively suppresses noise over a wide frequency spectrum, including low-frequency and high-frequency EMI.
- 4. Common mode chokes are compact and suitable for applications where space is limited.

### **Applications**

- 1. USB line for personal computers and peripheral
- 2. IEEE 1394 line for personal computers, DVC, STB
- 3. LVDS, panel line for liquid display panels, graph card,etc

#### **Product Information**

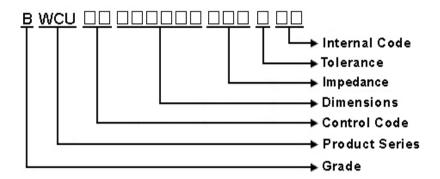
Series	Size Code (JIS/EIA)	Impedance (Ω)
BWCU	1608/0603	22 ~ 2200
	2012/0805	
	1210/0504	
	3216/1206	
	2520/1008	
	3225/1210	







- 1 Scope: This specification applies to BWCU Wire Wound Common Mode Choke Coil
- 2 Part Numbering:



3 Rating:

Operating Temperature:  $-40^{\circ}$ C  $\sim 105^{\circ}$ C

(Including self - temperature rise)

Storage Temperature:  $-40^{\circ}$ C  $\sim 105^{\circ}$ C

(The storage temperature range is for after the assembly)

4 Marking:

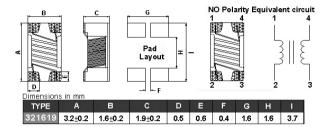
No Marking

### 5 Standard Testing Condition

	In case of doubt	
Temperature	Ordinary Temperature(15 to 35℃)	20 to 30℃
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



# 6 Configuration and Dimensions and Unit Weight:



Net Weight (grms)							
SIZE CODE	Net Weight (grms)						
261619	0.039 (typ.)						

### 7 Electrical Characteristics:

Part No.	Z (Ω)	RDC (Ω)Max.	IDC (mA)	Rated Voltage (Vdc)	Withstanding Voltage (Vdc)	Insulation Resistance (MΩ)(min)	Tolerance (±%)	Test Freq. (MHz)
BWCU00321619900 02	90	0.3	370	50	125	10	20,25	100
BWCU00321619121 02	120	0.3	370	50	125	10	20,25	100
BWCU00321619161 02	160	0.4	340	50	125	10	20,25	100
BWCU00321619171 02	170	0.4	330	50	125	10	20,25	100
BWCU00321619221 02	220	0.4	320	50	125	10	20,25	100
BWCU00321619261 02	260	0.5	310	50	125	10	20,25	100
BWCU00321619401 02	400	0.5	300	50	125	10	20,25	100
BWCU00321619501 02	500	0.6	280	50	125	10	20,25	100
BWCU00321619601 02	600	8.0	260	50	125	10	20,25	100
BWCU00321619102 = 02	1000	1	230	50	125	10	20,25	100
BWCU00321619222 02	2200	1.2	200	50	125	10	20,25	100

NOTE: □-tolerance M=±20% / Y=±25%

<sup>1.</sup> Operating temperature range  $-40 \,^{\circ}\text{C} \sim 105 \,^{\circ}\text{C}$  (Including self - temperature rise)

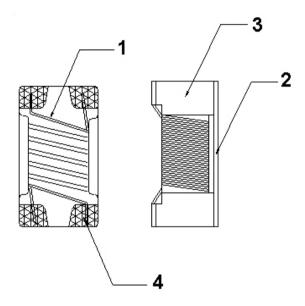
<sup>2.</sup>RDC: SINGLE WIRE TEST VALUE

<sup>3.</sup>IDC for Inductance drop 10% from its value without current.



# 8 BWCU00321619 Series

## 8.1 Construction:



### 8.2 Material List:

NO	PART	MATERIAL
1	WIRE	Grade 180
2	COVER SHEET	FERRITE CORE
3	CORE	FERRITE CORE
4	TERMINAL	Ag/Cu/Ni/Sn



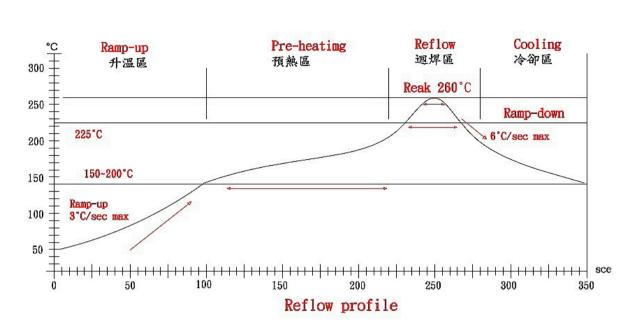
# 9 Common Mode Choke / RELIABILITY TEST 1-1.Environmental Performance

No	Item	Specification	Test Method				
1-1-1	Temperature Cycle	Appearance: No Damage	One cycle:				
		Impedance: within±20% of	Step	Temperature (°ℂ)	Time (min)		
		initial value	1	-40±3	30		
			2	25±2	3		
			3	105±3	30		
			4	25±2	3		
			Tota	l: 5 cycles			
			Meas	sured After Exposure in The Room	Condition For 1hrs		
1-1-2	High Temperature Resistance	1	Temperature: 105±3℃				
			Time	e: 1000Hrs			
			Meas	sured After Exposure In The Roon	Condition For 1Hrs		
1-1-3	Low Temperature Resistance		Tem	perature: -40±3°ℂ			
			Time	e: 1000Hrs			
			Meas	sured After Exposure In The Roon	Condition For 1Hrs		
1-1-4	Humidity Load Life	There should be no evidence	Tem	perature: 40±2℃			
		of short or open circle	Relative Humidity: 90~95%				
			Load	d: Allowed DC Current			
			Time	e: 96Hrs			

### 1-2.Mechanical Performance

No	Item	Specification	Test Method
1-2-1	Resistance To Soldering Heat	Appearance: No Damage	The device should be reflow soldered on PCB
			(peak 260°ℂ±5°ℂ for 10 seconds)
			2. Solder Composition: Sn/Ag3.0/Cu0.5
			3. Test time: 6 minutes
1-2-2	Solder ability	The electrodes shall be	1. Pre-Heating: 150℃,1min.
		at least 95% covered	2. Solder Composition: Sn/Ag3.0/Cu0.5
		with new solder coating	3. Solder Temperature: 245±5℃.
			4. Immersion Time: 4±1 sec.
1-2-3	Commponent Adhesion	1 Lbs. For 1210 Size	The device should be reflow soldered (245±5°C For
	(Push Test)	2 Lbs. For other	10 seconds) to a tinned copper substrate. A force guauge
			should be applied to the side of the component.
			The device must withstand a minimum force of 2 pounds
			without a failure of the termination attached to component





### Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	12	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

#### NOTE:

- 1.Re-flow possible times: within 3 times
- 2. Nitrogen adopted is recommendes while in re-flow
- 3. Products can only be soldered with reflow



### 10 Packaging:

### 10.1 Packaging -Cover Tape

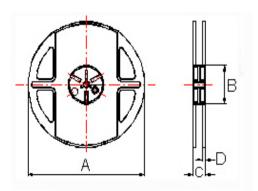
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



### 10.2 Packaging Quantity

TYPE	PCS/REEL
321619	2000

#### 10.3 Reel Dimensions



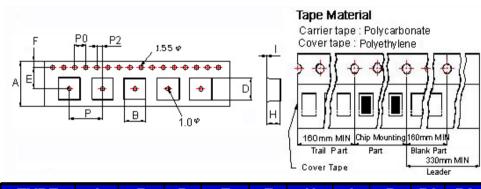
Dimensions in mm

TYPE	Α	В	ВС	
321619	178	60	12	1.5



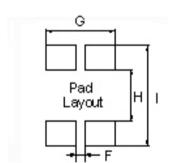
### 10 Packaging:

### 10.4 Tape Dimensions in mm



TYPE	Α	В	D	Ε	F	H		Р	P0	P2
321619	8	1.76	3.47	3.5	1.75	2.05	0.22	4	4	2

### 11 Recommended Land Pattern:



#### Dimensions in mm

TYPE	F(In/mm)	G(In/mm)	H(In/mm)	l(ln/mm)
321619	0.16/0.4	0.06/1.6	0.06/1.6	0.15/3.7

### 12 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. The storage period is less than 12 months. Be sure to follow the storage conditions (Temperature: 5 to 40°C, Humidity: 10 to 75% RHor less).
- If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
- 5.Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
- 6. The moisture sensitivity level (MSL) of products is classified as level 1.



